

**APPENDIX- SPECIFICATION  
MARKED TO SHOW CHANGES**

**CROSS-REFERENCE TO RELATED APPLICATIONS**

This application is a continuation-in-part of U.S. Application No. 09/651,779 (~~attorney docket number 108298515US~~), titled "Methods and Apparatus for Removing Conductive Material From a Microelectronic Substrate," filed August 30, 2000. Additionally, this application is related to, ~~and~~ U.S. Application No. 09/888,084 (attorney docket number 108298515US1), titled "Methods and Apparatus for Electrical, Mechanical and/or Chemical Removal of Conductive Material From a Microelectronic Substrate," filed June 21, 2001 ~~concurrently herewith~~, and U.S. Application No. 09/888,002 (attorney docket number 108298515US3), titled "Methods and Apparatus for Electrically and/or Chemically-Mechanically Removing Conductive Material From a Microelectronic Substrate," filed June 21, 2001 ~~concurrently herewith~~. All of the U.S. Patent Applications listed above are incorporated herein by reference, ~~all of which are incorporated herein in their entirety by reference.~~